

SPLC 2016

The 20th International Systems and Software Product Line Conference:
September 19th to 23rd, 2016 Beijing, China



IMPORTANT DATES

Abstract Submission:	March 7, 2016
Paper Submission:	March 14, 2016
Notification of Acceptance:	April 25, 2016
Camera-ready Paper Due:	May 23, 2016
Conference:	Sept. 19-23, 2016

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Kentaro Yoshimura, *Hitachi, Japan*

Research Track – Call For Papers

The Systems and Software Product Line Conference (SPLC) is a premier forum where researchers, practitioners, and educators can present and discuss the most recent ideas, trends, experiences, and challenges in the area of software and system product lines engineering.

The 20th SPLC will take place in Beijing, China, September 19-23, 2016.

For the research track, we invite high quality submissions describing original and unpublished results in all areas related to software product line engineering.

Topics (include but are not limited to)

- Domain analysis and requirements engineering
- Product line design, architecture, and implementation
- Variability management and product derivation
- Business, economics, organizational, and process issues
- Product line evolution and life-cycle
- Validation and verification
- Non-functional considerations
- Multi product lines, product lines of product lines
- Open source systems
- Software ecosystems and supply chains
- Incremental development of product lines
- Non-traditional applications of product line concepts

Submissions/Publishing:

- *Full papers* describing original results of conceptual, theoretical, empirical, and experimental research. The papers in this category must rely on theoretical and/or empirical evaluation.
- *Short papers* describing emerging technical and business directions, future trends, emerging ideas and outstanding challenges along with possible approaches for resolving them.

The page limit is 10 pages for full papers and 5 pages for short/vision papers. Submissions must follow the ACM proceedings format (<http://www.acm.org/publications/article-templates/proceedings-template.html/>) and will be reviewed by at least three members of the SPLC 2016 Research Track program committee.

The SPLC proceedings will be published by ACM in the ACM Digital Library within its International Conference Proceedings Series.

Submission System:

- *EasyChair*: <https://easychair.org/conferences/?conf=splc2016>

Further Information:

- SPLC 2016 will feature a *best paper award* for the Research Track.
- For all further information please refer to www.splc2016.net